捷多邦,专业PCB打样工厂,**SN54AC74** SN74AC74 DUAL POSITIVE-EDGE-TRIGGERED D-TYPE FLIP-FLOPS

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- **EPIC™** (Enhanced-Performance Implanted CMOS) 1-um Process
- **Package Options Include Plastic** Small-Outline (D), Shrink Small-Outline (DB), and Thin Shrink Small-Outline (PW) Packages, Ceramic Chip Carriers (FK), Flat (W), and DIP (J,N) Packages

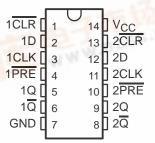
description

The 'AC74 are dual positive-edge-triggered D-type flip-flops.

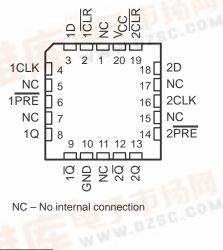
A low level at the preset (PRE) or clear (CLR) input sets or resets the outputs, regardless of the levels of the other inputs. When PRE and CLR are inactive (high), data at the data (D) input meeting the setup-time requirements is transferred to the outputs on the positive-going edge of the clock pulse. Clock triggering occurs at a voltage level and is not directly related to the rise time of the clock pulse. Following the hold-time interval, data at D can be changed without affecting the levels at the outputs.

The SN54AC74 is characterized for operation over the full military temperature range of -55°C to 125°C. The SN74AC74 is characterized for operation from -40°C to 85°C.

SN54AC74 ... J OR W PACKAGE SN74AC74 ... D, DB, N, OR PW PACKAGE (TOP VIEW)



SN54AC74 ... FK PACKAGE (TOP VIEW)



NC - No internal connection

FUNCTION TABLE

	INP	UTS	332	OUT	PUTS
PRE	CLR	CLK	D	Q	Q
L	CH.	X	Χ	Н	L
TH.	L	X	Χ	L	Н
L	L	X	Χ	H [†]	H [†]
Н	Н	\uparrow	Н	Н	L
Н	Н	\uparrow	L	L	Н
Н	Н	L	Χ	Q ₀	\overline{Q}_0

†This configuration is unstable; that is, it does not persist when either PRE or CLR returns to its inactive (high) level.

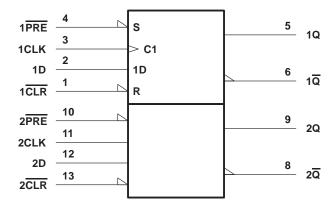
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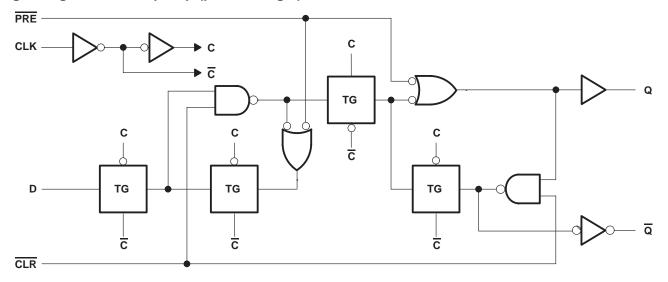
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logic symbol†



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for the D, DB, J, N, PW, and W packages.

logic diagram, each flip-flop (positive logic)



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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}		0.5 V to 7 V
Input voltage range, V _I (see Note 1)	0.5	V to V_{CC} + 0.5 V
Output voltage range, V _O (see Note 1)		V to V_{CC} + 0.5 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$)		±20 mA
Output clamp current, I _{OK} (V _O < 0 or V _O > V _{CC})		±20 mA
Continuous output current, $I_O(V_O = 0 \text{ to } V_{CC})$		±50 mA
Continuous current through V _{CC} or GND		±200 mA
Maximum power dissipation at $T_A = 55^{\circ}$ C (in still air) (see Note 2)): D package	1.25 W
	DB package	0.5 W
	N package	1.1 W
	PW package	0.5 W
Storage temperature range, T _{stg}		. −65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils, except for the N package, which has a trace length of zero.

recommended operating conditions (see Note 3)

			SN54	AC74	SN74/	AC74	UNIT
			MIN	MAX	MIN	MAX	UNII
Vcc	Supply voltage		2	6	2	6	V
		VCC = 3 V	2.1		2.1		
ViH	High-level input voltage	V _{CC} = 4.5 V	3.15		3.15		V
		V _{CC} = 5.5 V	3.85		3.85		
		V _{CC} = 3 V		0.9		0.9	
V _{IL} L	/ _{IL} Low-level input voltage	V _{CC} = 4.5 V		1.35		1.35	V
		V _{CC} = 5.5 V		1.65		1.65	
٧ı	Input voltage		0	VCC	0	VCC	V
٧o	Output voltage		0	VCC	0	VCC	V
		V _{CC} = 3 V		-12		-12	
IOH	High-level output current	V _{CC} = 4.5 V		-24		-24	mA
		V _{CC} = 5.5 V		-24		-24	
		VCC = 3 V		12		12	
loL	Low-level output current	V _{CC} = 4.5 V		24		24	mA
		V _{CC} = 5.5 V		24		24	
Δt/Δν	Input transition rise or fall rate		0	8	0	8	ns/V
T _A	Operating free-air temperature		- 55	125	-40	85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	1,,	T	A = 25°C	;	SN54	AC74	SN74	AC74	UNIT	
PARAMETER	TEST CONDITIONS	v _{CC}	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT	
		3 V	2.9	4.49		2.9		2.9			
	I _{OH} = -50 μA	4.5 V	4.4	5.49		4.4		4.4			
		5.5 V	5.4	5.49		5.4		5.4			
VOH	$I_{OH} = -12 \text{ mA}$	3 V	2.56			2.4		2.46		٧	
VOH	I _{OH} = -24 mA	4.5 V	3.86			3.7		3.76		V	
	10H = -24 IIIA	5.5 V	4.86			4.7		4.76			
	$I_{OH} = -50 \text{ mA}^{\dagger}$	5.5 V				3.85					
	$I_{OH} = -75 \text{ mA}^{\dagger}$	5.5 V						3.85			
		3 V		0.002	0.1		0.1		0.1		
	I _{OL} = 50 μA	4.5 V		0.001	0.1		0.1		0.1		
		5.5 V		0.001	0.1		0.1		0.1		
1	I _{OL} = 12 mA	3 V			0.36		0.5		0.44	V	
VOL	I _{OL} = 24 mA	4.5 V			0.36		0.5		0.44	v	
	IOL = 24 IIIA	5.5 V			0.36		0.5		0.44		
	$I_{OL} = 50 \text{ mA}^{\dagger}$	5.5 V					1.65				
	$I_{OL} = 75 \text{ mA}^{\dagger}$	5.5 V							1.65		
Data pins	S VI – Voc or CND	5.5 V			±0.1		±1		±1		
Control p	$V_I = V_{CC}$ or GND	5.5 V			±0.1		±1		±1	μA	
Icc	$V_I = V_{CC}$ or GND, $I_O = 0$	5.5 V			2		40		20	μΑ	
Ci	V _I = V _{CC} or GND	5 V		3						pF	

Thot more than one output should be tested at a time, and the duration of the test should not exceed 2 ms.

timing requirements over recommended operating free-air temperature range, V_{CC} = 3.3 V $\,\pm\,$ 0.3 V (unless otherwise noted) (see Figure 1)

			T _A = 2	T _A = 25°C		25°C SN54AC74		AC74	SN74AC74		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	UNIT		
fclock	Clock frequency		0	100	0	100	0	100	MHz		
	t _w Pulse duration	PRE or CLR low	5.5		8		7		no		
t _W	ruise duration	CLK	5.5		8		7		ns		
		Data	4		5		4.5				
t _{su} Se	Setup time, data before CLK↑ PRE or CLR inactive		0		0.5		0		ns		
th	Hold time, data after CLK↑	·	0.5		0.5		0.5		ns		

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timing requirements over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V (unless otherwise noted) (see Figure 1)

			T _A = 2	25°C	SN54	AC74	SN74/	AC74	UNIT	
			MIN	MAX	MIN	MAX	MIN	MAX	UNIT	
fclock	Clock frequency		0	140	0	140	0	140	MHz	
	tw. Pulse duration	PRE or CLR low	4.5		5.5		5		ns	
t _w	ruise dui auori	CLK	4.5		5.5		5		110	
	Oates face data before OLKA	Data	3		4		3		ns	
t _{su}	Setup time, data before CLK↑		0		0.5		0		115	
th	Hold time, data after CLK↑		0.5		0.5	·	0.5	·	ns	

switching characteristics over recommended operating free-air temperature range, V_{CC} = 3.3 V $\,\pm\,$ 0.3 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	FROM TO		T _A = 25°C			SN54AC74		SN74AC74	
PARAMETER	(INPUT)	(OUTPUT)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
f _{max}			100	125		70		95		MHz
^t PLH		PRE or CLR Q or Q	3.5	8	12	1	13	2.5	13	20
^t PHL	PRE OF CLR		4	10.5	12	1	14	3.5	13.5	ns
t _{PLH}	CLK	<u> </u>	4.5	8	13.5	1	17.5	4	16	ns
t _{PHL}	OLK	Q or $\overline{\mathbb{Q}}$	3.5	8	14	1	13.5	3.5	14.5	115

switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V $\,\pm\,$ 0.5 V (unless otherwise noted) (see Figure 1)

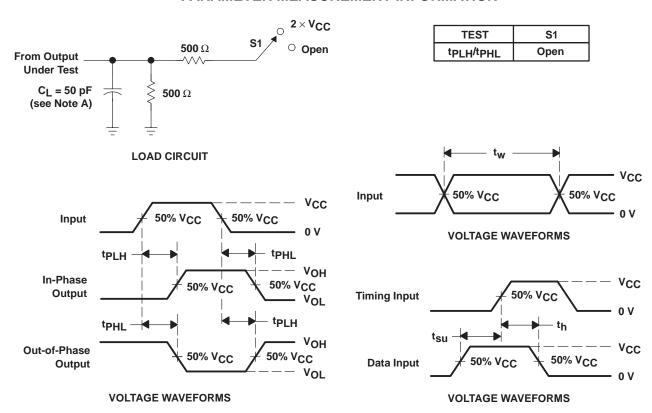
PARAMETER	FROM TO		T _A = 25°C			SN54AC74		SN74AC74		UNIT
PARAMETER	(INPUT)	(OUTPUT)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
fmax			140	160		95		125		MHz
t _{PLH}		PRE or CLR Q or Q	2.5	6	9	1	9.5	2	10	20
t _{PHL}	PRE OF CLR		3	8	9.5	1	10.5	2.5	10.5	ns
t _{PLH}	CLK	IV 0 =	3.5	6	10	1	12	3	10.5	ns
t _{PHL}	OLK	Q or Q	2.5	6	10	1	10	2.5	10.5	115

operating characteristics, $V_{CC} = 3.3 \text{ V}$, $T_A = 25^{\circ}\text{C}$

PARAMETER		TEST CON	TYP	UNIT	
C _{pd}	Power dissipation capacitance	C _L = 50 pF,	f = 1 MHz	45	pF

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PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, Z_O = 50 Ω , $t_f \leq$ 2.5 ns, $t_f \leq$ 2.5 ns.
- C. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

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